

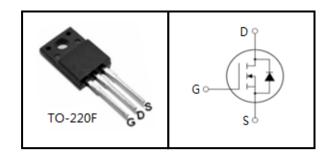
## **650V N-Channel MOSFET**

#### **FEATURES**

- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

#### **APPLICATIONS**

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)



Device Marking and Package Information					
Device	Package	Marking			
CS12N65FF	TO-220F	CS12N65FF			

<b>Absolute Maximum Ratings</b> $T_C = 25^{\circ}C$ , unless otherwise noted							
_	Symbol	Value	T				
Parameter		TO-220F	Unit				
Drain-Source Voltage (V <sub>GS</sub> = 0V)	V <sub>DSS</sub>	650	V				
Continuous Drain Current	I <sub>D</sub>	12	Α				
Pulsed Drain Current (note1)	I <sub>DM</sub>	48	Α				
Gate-Source Voltage	V <sub>GSS</sub>	±30	V				
Single Pulse Avalanche Energy (note2)	E <sub>AS</sub>	352.8	mJ				
Avalanche Current (note1)	I <sub>AS</sub>	8.4	Α				
Repetitive Avalanche Energy (note1)	E <sub>AR</sub>	211.68	mJ				
Power Dissipation (T <sub>C</sub> = 25°C)	$P_{D}$	65	W				
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55~+150	°C				

Thermal Resistance				
		Value		
Parameter	Symbol	TO-220F	Unit	
Thermal Resistance, Junction-to-Case	R <sub>thJC</sub>	1.92	°C/W	
Thermal Resistance, Junction-to-Ambient	R <sub>thJA</sub>	62.5		



<b>Specifications</b> $T_J = 25^{\circ}C$ , unless otherwise noted								
Doromotor		Total October 1985	Value			11.24		
Parameter Symbol Test		Test Conditions	Min.	Тур.	Max.	Unit		
Static								
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_{D} = 250\mu A$	650			V		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 650V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	μΑ		
Gate-Source Leakage	I <sub>GSS</sub>	$V_{GS} = \pm 30V$			±100	nA		
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		4.0	٧		
Drain-Source On-Resistance (Note3)	R <sub>DS(on)</sub>	$V_{GS} = 10V, I_D = 6.0A$		0.55	0.68	Ω		
Dynamic								
Input Capacitance	C <sub>iss</sub>			1750	1	pF		
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0V$		157	-			
Reverse Transfer Capacitance	$C_{rss}$	$V_{DS} = 25V$ , $f = 1.0MHz$		4.5				
Internal Gate Resistance	Rg			1.1		Ω		
Total Gate Charge	$Q_g$			32	-	nC		
Gate-Source Charge	$Q_{gs}$	$V_{DD} = 520V, I_{D} = 12A,$ $V_{GS} = 10V$		8.78				
Gate-Drain Charge	$Q_{gd}$			11.4				
Turn-on Delay Time	t <sub>d(on)</sub>			43		ns		
Turn-on Rise Time	t <sub>r</sub>	V <sub>DD</sub> = 325V, I <sub>D</sub> =12A,		20	1			
Turn-off Delay Time	$t_{d(off)}$	$R_G = 25 \Omega$		122	1			
Turn-off Fall Time	t <sub>f</sub>			39	1			
Drain-Source Body Diode Character	istics							
Continuous Body Diode Current	Is	T 05.00			12	A		
Pulsed Diode Forward Current	I <sub>SM</sub>	T <sub>C</sub> = 25 °C			48			
Body Diode Voltage	$V_{SD}$	$T_J = 25^{\circ}\text{C}, I_{SD} = 6\text{A}, V_{GS} = 0\text{V}$			1.4	٧		
Reverse Recovery Time	t <sub>rr</sub>	$V_{GS} = 0V, I_{S} = 12A,$		348		ns		
Reverse Recovery Charge	$Q_{rr}$	di <sub>F</sub> /dt =100A /µs		4.5		μC		

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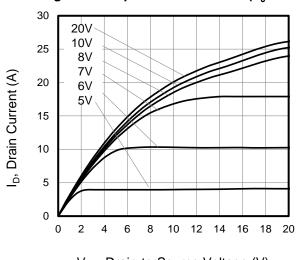
#### Notes

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. L = 10.0mH,  $V_{DD}$  = 50V,  $R_G$  = 25  $\Omega$ , Starting  $T_J$  = 25  $^{\circ}C$
- 3. Pulse Test: Pulse width ≤ 300µs, Duty Cycle ≤ 1%



## **Typical Characteristics** $T_J = 25^{\circ}C$ , unless otherwise noted

Figure 1. Output Characteristics ( $T_J = 25^{\circ}C$ )



V<sub>DS</sub>, Drain-to-Source Voltage (V)

Figure 3. Drain Current vs. Temperature

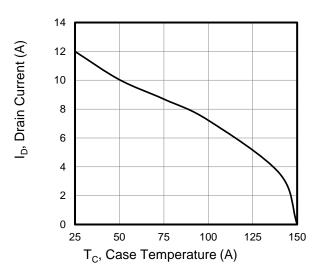


Figure 5. Transfer Characteristics

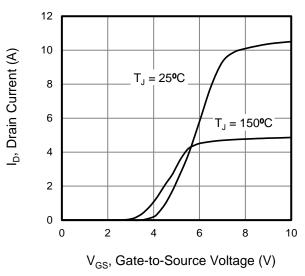


Figure 2. Body Diode Forward Voltage

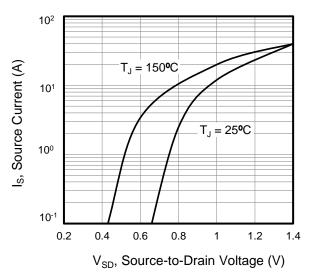
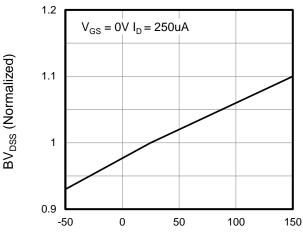
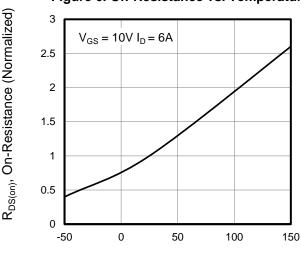


Figure 4. BV<sub>DSS</sub> Variation vs. Temperature



T<sub>J</sub>, Junction Temperature (°C)

Figure 6. On-Resistance vs. Temperature



 $T_J$ , Junction Temperature ( ${}^{\rm o}{\rm C}$ )



### **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

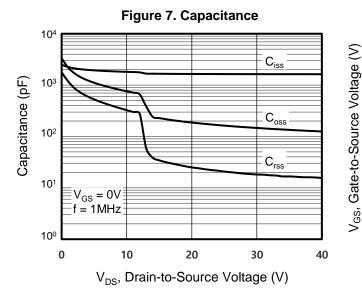
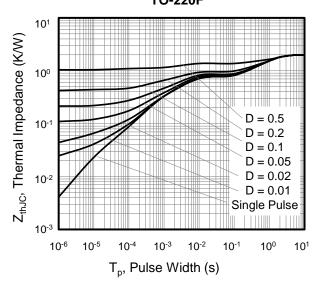


Figure 8. Gate Charge  $V_{DD} = 130V$   $V_{DD} = 325V$   $V_{DD} = 520V$   $V_{DD} = 520V$ 

Figure 9. Transient Thermal Impedance TO-220F



 $Z_{\text{thJC}}$ , Thermal Impedance (K/W)



Figure A: Gate Charge Test Circuit and Waveform

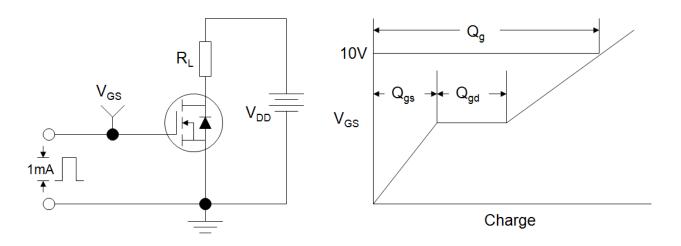


Figure B: Resistive Switching Test Circuit and Waveform

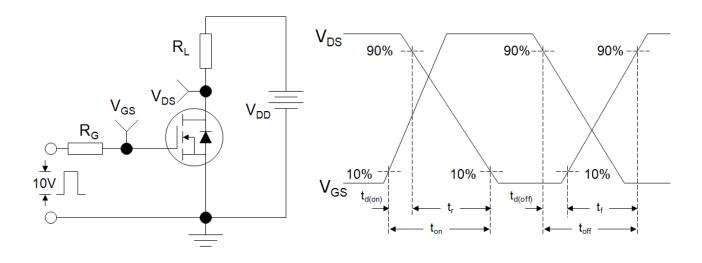
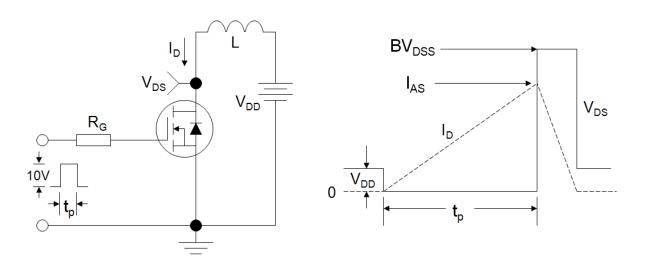
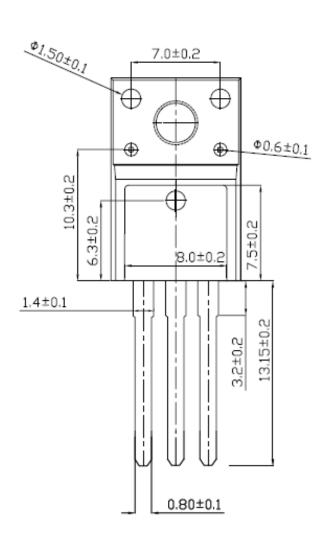


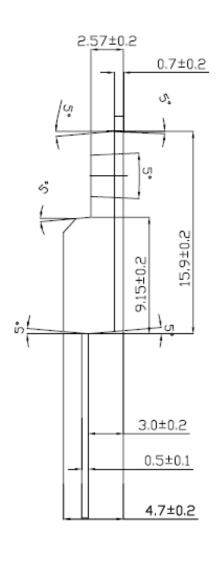
Figure C: Unclamped Inductive Switching Test Circuit and Waveform





# **TO-220F**







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